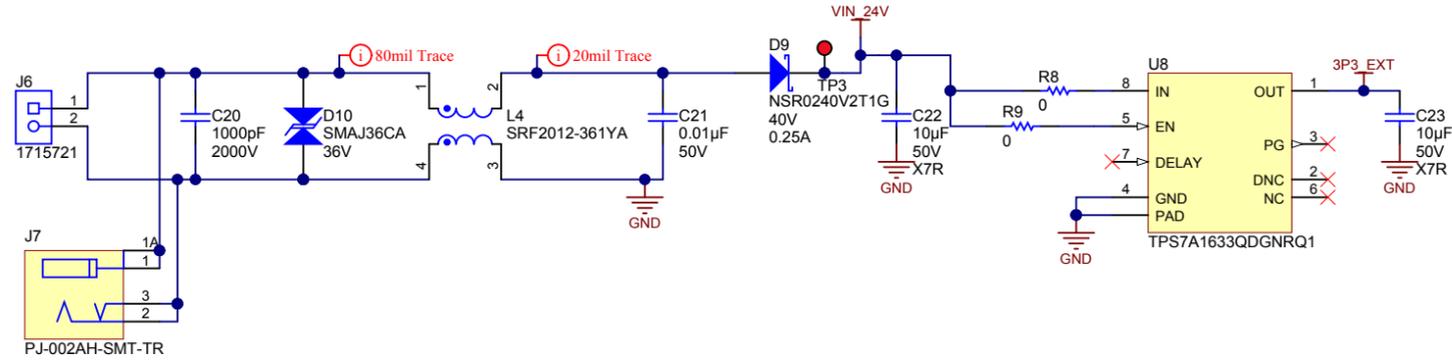
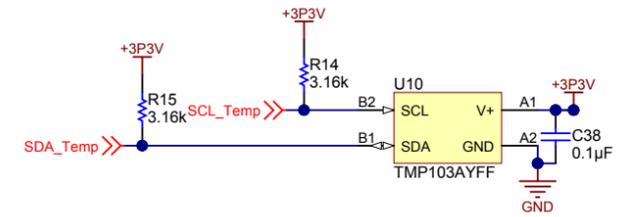
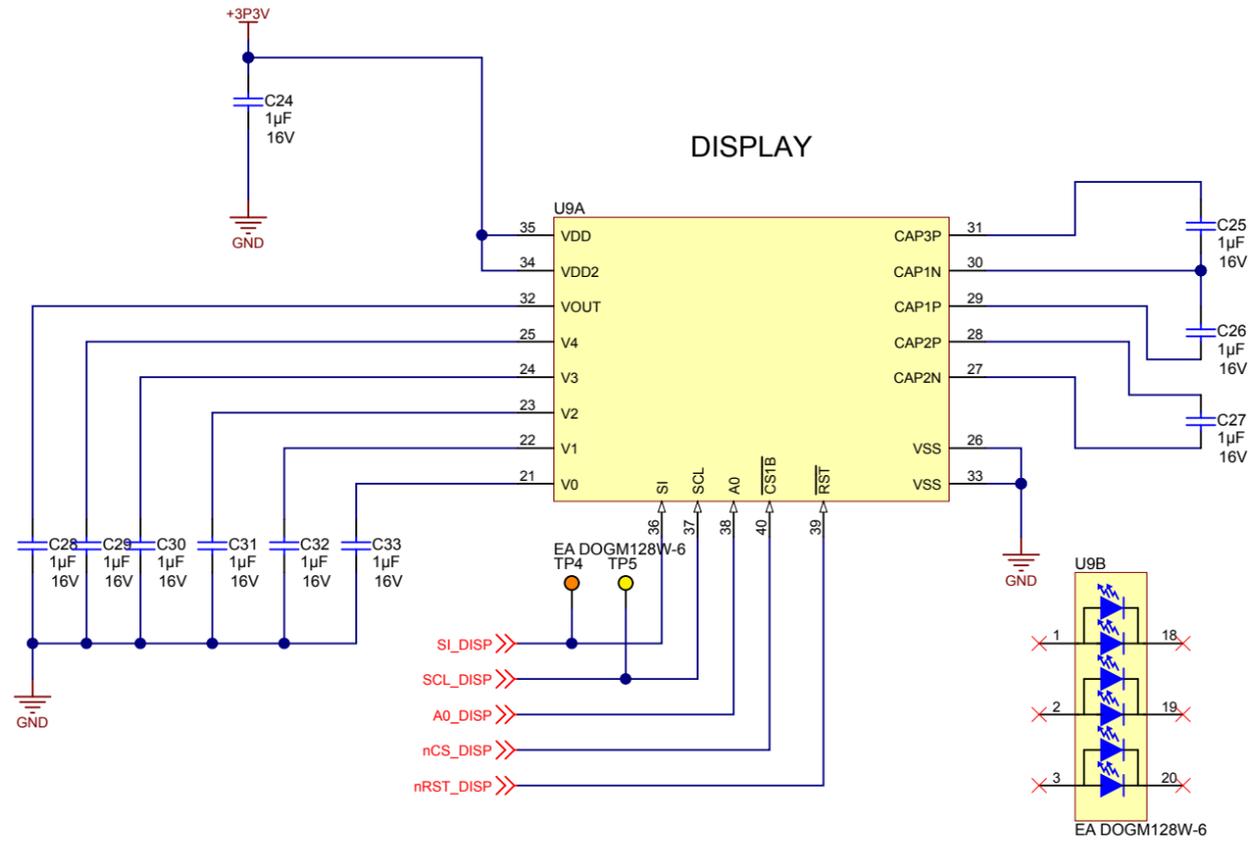


### Vin Connectors & EMI Protection



### DISPLAY



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Number: ISE4016	Rev: E2	Designed for: Public Release	Mod. Date: 7/3/2014
SVN Rev: Not in version control	Sheet Title:	Project Title: ISE4016	
Drawn By:	Assembly Variant: 001	File: Power_SchDoc	Sheet: 1 of 1
Engineer: Ajinder Singh	Size: B	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

~~DNP~~  
FID1   ~~DNP~~  
FID2   ~~DNP~~  
FID3   ~~DNP~~  
FID4   ~~DNP~~  
FID5   ~~DNP~~  
FID6

PCB Number: ISE4016  
PCB Rev: E2

PCB  
LOGO  
Texas Instruments

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: ISE4016		Rev: E2	Designed for: Public Release	Mod. Date: 9/3/2014
SVN Rev: Not in version control		Project Title: ISE4016		 http://www.ti.com © Texas Instruments 2014
Drawn By:		Sheet Title:		
Engineer: Ajinder Singh		Assembly Variant: 001	Sheet: 1 of 1	
File: Hardware_ANSI-B_SchDoc			Size: B	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>

Revision History	
Revision	Notes

Place Block Diagram here (if appropriate) or delete this text box.  
 If using a block diagram from another tool, save the picture as a .bmp file.  
 Then, use menu Place|Drawing Tools|Graphic to insert the .bmp file on the schematic.

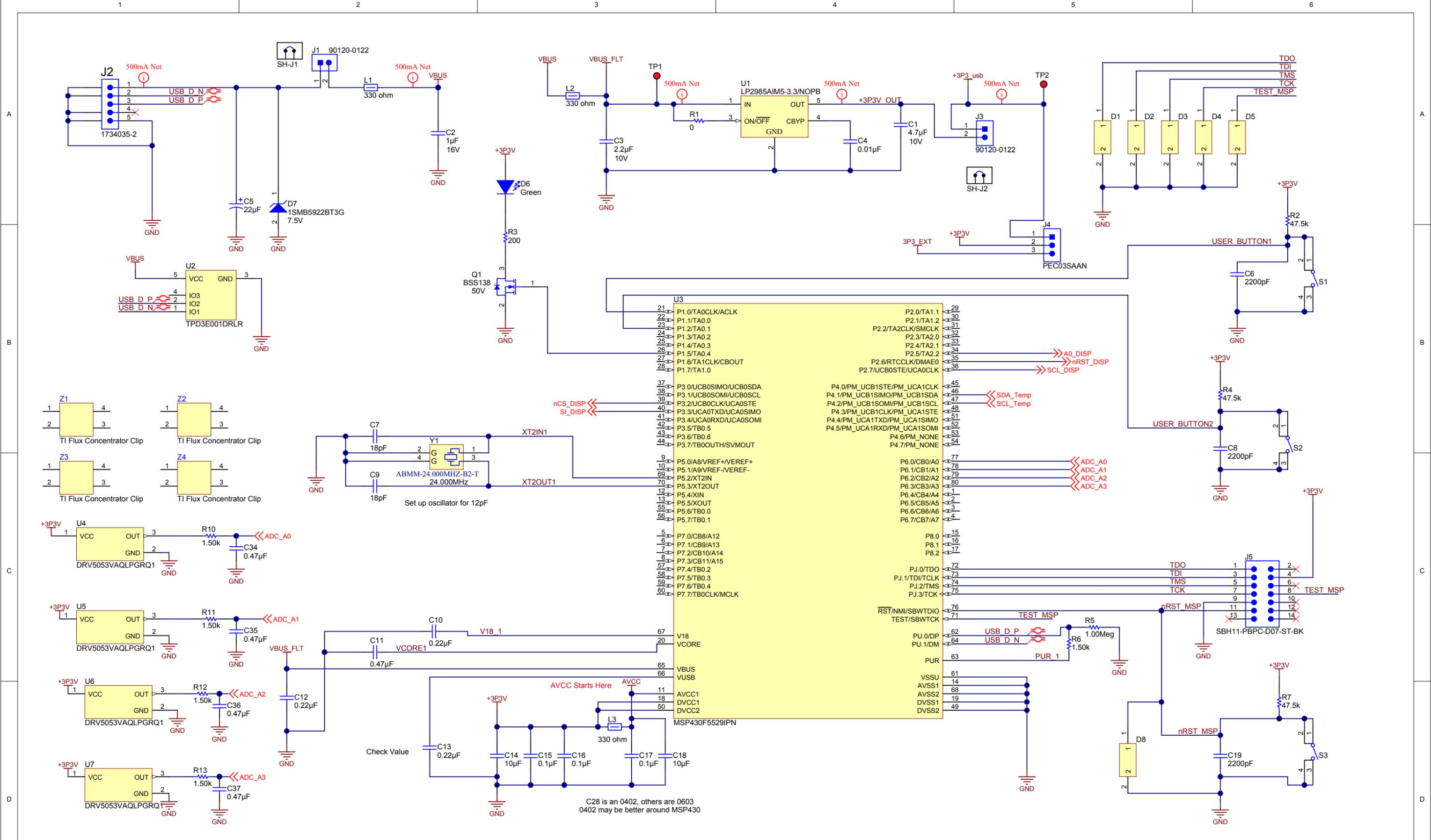
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Number: ISE4016	Rev: E2	Designed for: Public Release	Mod. Date: 7/3/2014
SVN Rev: Not in version control	Assembly Variant: 001	Sheet Title:	Sheet: 1 of 1
Drawn By:	File: Cover Sheet_ANSI-B_SchDoc	Size: B	
Engineer: Ajinder Singh	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



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Number: ISE4016		Rev: E2	Designed for: Public Release		Mod. Date: 7/3/2014
SVN Rev: Not in version control		Assembly Variant: 001		Sheet: 1 of 1	
Drawn By:		File: BlankSheet_ANSI-B_SchDoc		Size: B	
Engineer: Ajinder Singh		Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		 <a href="http://www.ti.com">http://www.ti.com</a> <small>© Texas Instruments 2014</small>	



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